

APPLICATION NO. 09/944344		CONT/PRIOR F	CLASS 205	SUBCLASS 291	ART UNIT 1741	EXAMINER Wong
APPLICANTS Shiroshi Matsuki Kazunori Akiyama						
TITLE Material for copper electroplating and copper electroplating method						
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PTO-2040 12/89						

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	(Assistant Examiner) _____ (Date) _____			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____	(Primary Examiner) _____ (Date) _____			ISSUE FEE	
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